

3A, 50V - 600V Super Fast Surface Mount Rectifier

FEATURES

- AEC-Q101 qualified
- Glass passivated chip junction
- Ideal for automated placement
- Low profile package
- Super fast recovery time for high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Automotive application
- Car lighting
- Snubber
- · Freewheeling application

MECHANICAL DATA

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- · Polarity: Indicated by cathode band
- Weight: 0.110g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I _F	3	Α		
V_{RRM}	50 - 600	V		
I _{FSM}	100	Α		
T _{J MAX}	150	°C		
Package	DO-214AA (SMB)			
Configuration	Single die			





DO-214AA (SMB)



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)										
PARAMETER	SYMBOL	ES3	ES3	ES3	ES3	ES3	ES3	ES3	ES3	UNIT
T ANAME I EN		ABH	BBH	CBH	DBH	FBH	GBH	HBH	JBH	
Marking code on the device		ES	ES	ES	ES	ES	ES	ES	ES	
Marking code on the device		3AB	3BB	3CB	3DB	3FB	3GB	3HB	3JB	
Repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	500	600	V
Reverse voltage, total rms value	$V_{R(RMS)}$	35	70	105	140	210	280	350	420	V
Forward current	I _F	3				Α				
Surge peak forward current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	100				Α				
Junction temperature	T _J	T _J - 55 to +150			°C					
Storage temperature	T _{STG}	- 55 to +150			°C					



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THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-lead thermal resistance	R _{OJL}	24	°C/W		
Junction-to-ambient thermal resistance	R _{OJA}	84	°C/W		
Junction-to-case thermal resistance	R _{eJC}	26	°C/W		

Thermal Performance Note: Units mounted on PCB (10mm x 10mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (TA = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
	ES3ABH ES3BBH ES3CBH ES3DBH	I _F = 1.5A, T _J = 25°C	V _F	0.80	0.92	V
	ES3FBH ES3GBH			0.90	1.04	V
	ES3HBH ES3JBH			1.11	1.30	V
	ES3ABH ES3BBH ES3CBH ES3DBH	J 004 T 0500	V	0.86	1.00	V
	ES3FBH ES3GBH	$I_F = 3.0A, T_J = 25^{\circ}C$	V _F	0.98	1.13	V
Forward voltage ⁽¹⁾	ES3HBH ES3JBH			1.24	1.45	V
Forward voltage	ES3ABH ES3BBH ES3CBH ES3DBH	I _F = 1.5A, T _J = 125°C	V_{F}	0.66	0.75	V
	ES3FBH ES3GBH			0.73	0.85	V
	ES3HBH ES3JBH			0.85	0.98	V
	ES3ABH ES3BBH ES3CBH ES3DBH	1 2 0 A T 40500	V_{F}	0.73	0.84	V
	ES3FBH ES3GBH	$I_F = 3.0A, T_J = 125$ °C		0.83	0.95	V
	ES3HBH ES3JBH			0.99	1.13	V
Reverse current @ rated V _R ⁽²⁾		T _J = 25°C		-	10	μA
		T _J = 125°C	I _R	-	100	μΑ
lungtion congeitance	ES3ABH ES3BBH ES3CBH ES3DBH	1MHz, V _R = 4.0V	CJ	46	-	pF
Junction capacitance	ES3FBH ES3GBH			41	-	pF
	ES3HBH ES3JBH			34	-	pF
Reverse recovery time		$I_F = 0.5A$, $I_R = 1.0A$ $I_{rr} = 0.25A$	t _{rr}	-	35	ns

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms



ORDERING INFORMATION				
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING		
ES3xBH	DO-214AA (SMB)	3,000 / Tape & Reel		

Notes:

1. "x" defines voltage from 50V(ES3ABH) to 600V(ES3JBH)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

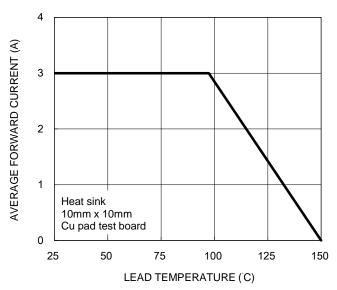


Fig.2 Typical Junction Capacitance

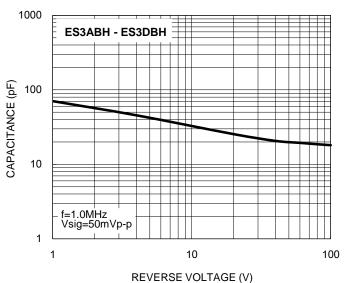


Fig.3 Typical Reverse Characteristics

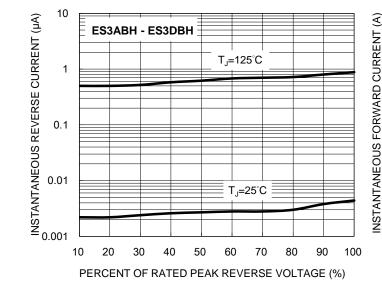
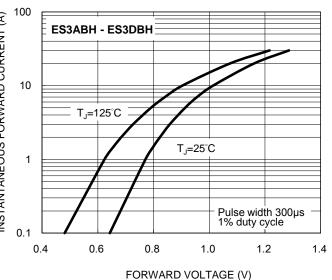


Fig.4 Typical Forward Characteristics





CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.5 Typical Junction Capacitance

Fig.6 Typical Reverse Characteristics

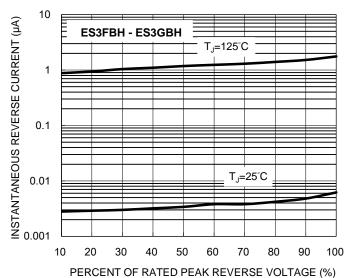
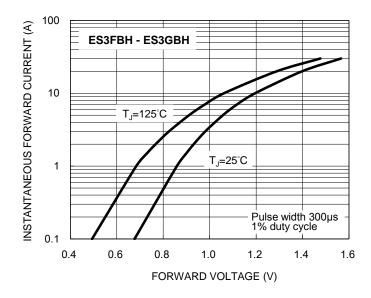


Fig.7 Typical Forward Characteristics





CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.8 Typical Junction Capacitance

Fig.9 Typical Reverse Characteristics

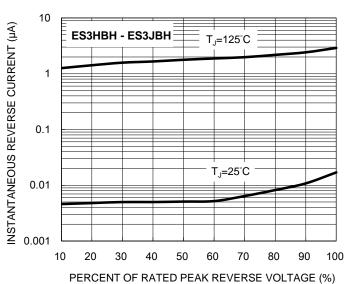
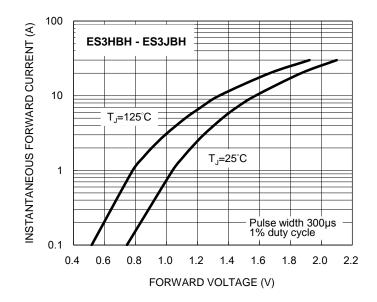


Fig.10 Typical Forward Characteristics

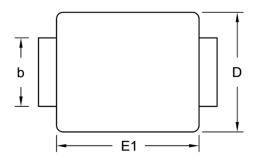


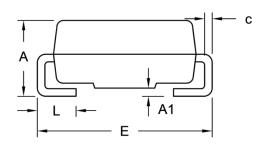


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PACKAGE OUTLINE DIMENSIONS

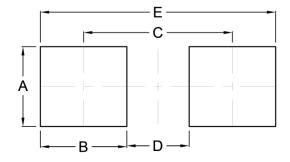
DO-214AA (SMB)





DIM.	Unit (mm)		Unit ((inch)	
DIIVI.	Min.	Max.	Min.	Max.	
Α	1.95	2.65	0.077	0.104	
A1	0.05	0.20	0.002	0.008	
b	1.95	2.20	0.077	0.087	
С	0.15	0.31	0.006	0.012	
D	3.30	3.95	0.130	0.156	
E	5.10	5.60	0.201	0.220	
E1	4.05	4.60	0.159	0.181	
L	0.75	1.60	0.030	0.063	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	2.30	0.091
В	2.50	0.098
С	4.30	0.169
D	1.80	0.071
E	6.80	0.268

MARKING DIAGRAM



P/N = Marking Code
G = Green Compound
YW = Date Code
F = Factory Code

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